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IEEE EPS Webinar – Advancement in Copper Wire Bond

Dec 23rd, 2024

EPS Webinar Series

Advancement in Cu Wire Bond

Date	: 23-Dec-24 (Mon)
Venue	: CISCO Webex
Time	: 9.00am – 10.00am

Abstract:

Copper wire bonding in IC packaging faces challenges with advanced wafer node and higher performance application. Hence, breakthrough wire bond method needed to prevent pad crack, achieve good bonding integrity, IMC coverage, and reliability.

Hiew Pey Fang

Principal Staff Engineer
NXP Semiconductors Malaysia

Register Here: https://shorturl.at/YQplh

Organized by :

- IEEE EPS Malaysia has organized a Technical Webinar on Dec 23rd 2024 on Advancement in Copper Wire Bond.
- Miss Hiew Pey Fang who is currently IEEE EPS member, and a Copper Wire Bond expert as well as Principal Staff Engineer in NXP Semiconductors, Package Innovation Dept, has provided a very good overview on the fundamentals in Copper Wire Bond process, including key challenges and resolutions through breakthrough wire bonding concept to achieve good bonding reliability.
- Event was attended by 24 participants including IEEE EPS members worldwide .